

FEATURES

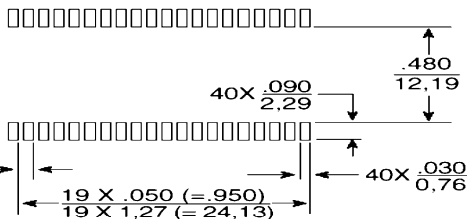
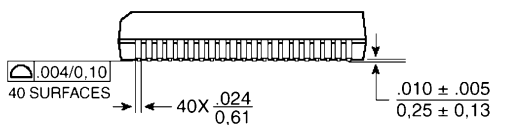
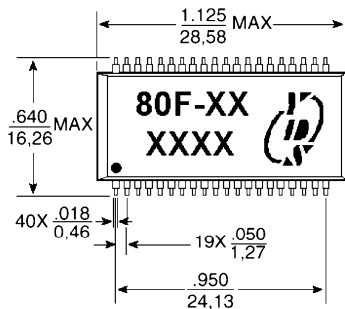
- IC-grade transfer molded package withstands 235°C peak temperature profile.



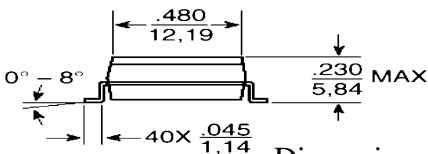
ELECTRICAL SPECIFICATIONS @25°C-Operating temperature 0°C TO 70°C

Part Number	Transformer Turns Ratio (±2%)		Sine Wave Inductance OCL (μ H min)	Interwinding Capacitance C _{WW} (Pf max)	Leakage Inductance L _L (μ H max)	Return Loss 5 to 10 MHz (dB min)		Common Mode Rejection (dB min) XMIT					Hipot (V _{RMS} min)
	RCV	XMIT				100Ω	98±13Ω	5 MHz	10 MHz	50 MHz	100 MHz	200 MHz	
80F-11	1:1	1CT:1CT	180	10	0.30	-20	-15	-40	-30	-20	-15	-10	1500
80F-12	1:1	1CT:1CT	150	10	0.30	-20	-15	-60	-50	-30	-20	-15	1500
80F-13	1:1	1CT:1CT	150	10	0.30	-20	-15	-60	-60	-40	-30	-20	1500

MARKINGS AND DIMENSION



Suggested SMD Pad Layout

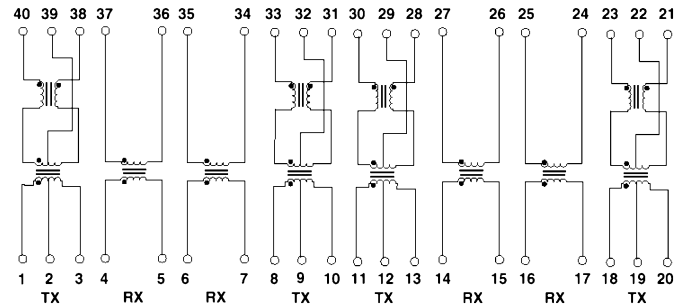


Dimensions:inches/mm

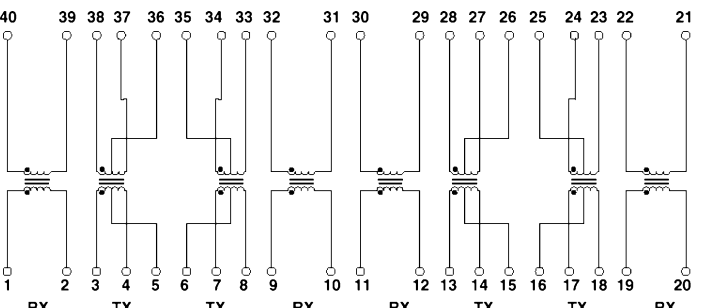
Unless otherwise specified, all tolerances are ±.010/±0.25

SCHEMATIC

80F-11



80F-12



80F-13

